



## ALLIANCE MEMORY MDS REPORT

Part Number:		<b>AS4C8M16SA-6BAN</b> <b>AS4C8M16SA-6BIN</b> <b>AS4C8M16SA-7BCN</b>								
Part Weight:		131.9mg								
No.	Part Name	Material Name	Component wt (mg)	Material Content (Element)	CAS Number	Element wt (%)	Element wt (mg)	wt % of Total unit wt	PPM	
1	Substrate	HL-832NX / AUS 308	37.39365	Bismaleimide Triazine resin	105391-33-1	6.99%	2.61561	1.98%	69948	
				Epoxy resin -1	25722-66-1	6.99%	2.61561	1.98%	69948	
				Epoxy resin -2	9003-36-5	6.99%	2.61561	1.98%	69948	
				Inorganic Filler	21645-51-2	15.74%	5.88512	4.46%	157383	
				Continuous Filament Fiber Glass	65997-17-3	21.57%	8.06480	6.11%	215673	
				Talc containing no asbestiform fibers	14807-96-6	0.45%	0.16797	0.13%	4492	
				Morpholine derivative	Trade secret	0.45%	0.16797	0.13%	4492	
				Barium sulfate	7727-43-7	5.05%	1.88969	1.43%	50535	
				Silica, amorphous	7631-86-9	0.11%	0.04199	0.03%	1123	
				Dipropylene glycol monomethyl ether	34590-94-8	2.70%	1.00783	0.76%	26952	
				Epoxy resin A	Trade secret	1.46%	0.54591	0.41%	14599	
				Epoxy resin B	85954-11-6	1.01%	0.37794	0.29%	10107	
				Copper	7440-50-8	29.79%	11.13957	8.45%	297900	
Nickel	7440-02-0	0.61%	0.22810	0.17%	6100					
Gold	7440-57-5	0.08%	0.02991	0.02%	800					
2	Mold compound	G1250	73.9959	Epoxy resin	Trade Secret	5.50%	4.06977	3.09%	55000	
				Phenol resin	Trade Secret	4.50%	3.32982	2.52%	45000	
				Carbon Black	1333-86-4	0.30%	0.22199	0.17%	3000	
				Silica Fused	60676-86-0	89.70%	66.37432	50.32%	897000	
3	Epoxy	2025D	0.27699	Silica, amorphous, fused	Trade Secret	54.50%	0.15096	0.11%	545000	
				Bismaleimide monomer	Trade Secret	27.50%	0.07617	0.06%	275000	
				Acrylate monomer	Trade Secret	7.50%	0.02077	0.02%	75000	
				Epoxy Resin	Trade Secret	7.50%	0.02077	0.02%	75000	
				Acrylic resin	112-15-2	3.00%	0.00831	0.01%	30000	
4	Solder Ball	Sn/Ag/Cu	16.0918	Tin	7440-31-5	96.50%	15.52859	11.77%	965000	
				Silver	7440-22-4	3.00%	0.48275	0.37%	30000	
				Copper	7440-50-8	0.50%	0.08046	0.06%	5000	
5	Gold wire	Au	0.55398	gold	7440-57-5	100.00%	0.55398	0.42%	1000000	
6	Die	Chip	3.58768	Silicon	7440-21-3	100.00%	3.58768	2.72%	1000000	
			131.9				600.00%	131.90000	100.00%	6000000